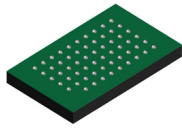
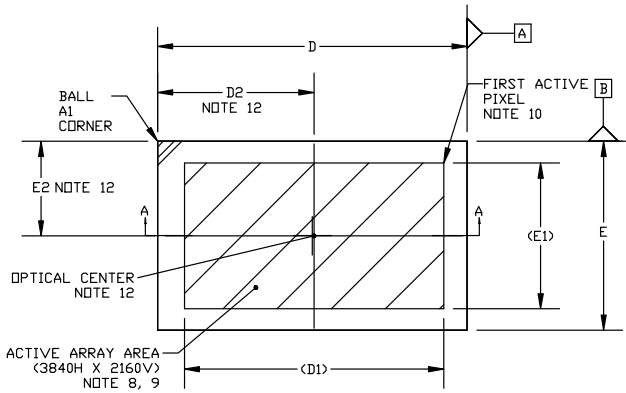


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



CSP59 6.41x3.91x0.62, 0.50P CASE 570AV ISSUE B

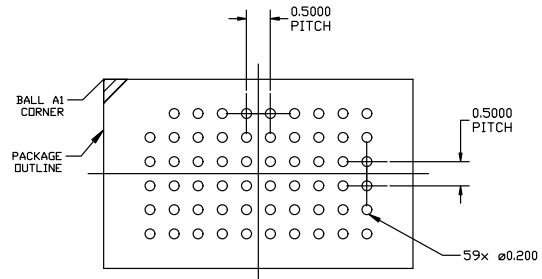
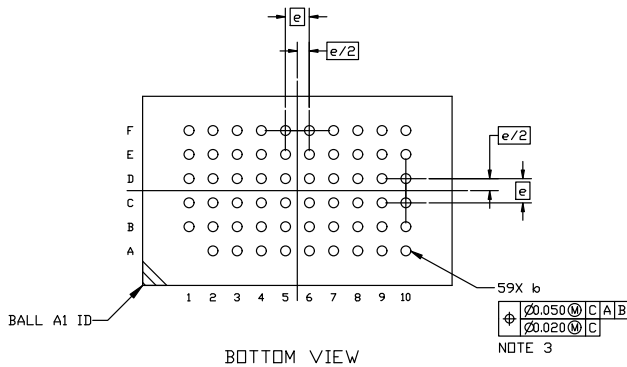
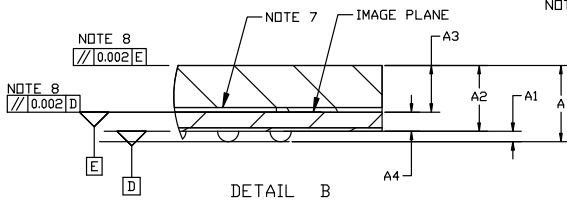
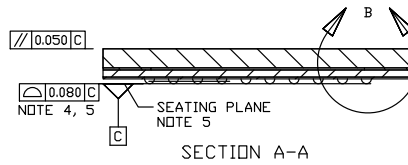
DATE 28 JUL 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS (mm).
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.044 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.035, -0.005).

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.783
A1	0.070	0.100	0.130
A2	0.566	0.626	0.686
A3	0.424	0.444	0.464
A4	0.142	0.182	0.222
b	0.170	0.200	0.230
D	6.392	6.419	6.446
D1	5.376 REF		
D2	3.217	3.244	3.271
E	3.889	3.916	3.943
E1	3.024 REF		
E2	1.936	1.963	1.990
e	0.500 BSC		
e2	0.250 BSC		



*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SLDERRM/D.

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